

RELIABILITY MONITOR REPORT  
FOR

**Flip Chip Package**

**Dallas Semiconductor**

4401 South Beltwood Parkway  
Dallas, TX 75244-3292

This Report was prepared by  
Dallas Semiconductor Reliability Engineering

**Summary:**

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The specific assemblies included in this package monitor are:

ASSY SITE	PINS PACKAGE
Dallas-8"	2 Flip Chip RDL no encap

Note: Due to the nature of the construction on this assembly, there is no operating life data collected.

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between and

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**Assembly Information:**

Package Type: Flip Chip RDL (Solder Bump)  
Flammability: UL 94-V0  
Date Code Range: 0639 to 0642

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**STORAGE LIFE**

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
STORAGE LIFE	0639	DS2502	150C	1000 HRS	231	0	
<b>Total:</b>						<b>0</b>	

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**TEMPERATURE CYCLE**

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
TEMP CYCLE	0642	DS2502	-40 TO 85C	1000 CYS	80	0	
TEMP CYCLE	0642	DS2502	-40 TO 85C	1000 CYS	80	0	
<b>Total:</b>						<b>0</b>	

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**TEMPERATURE HUMIDITY BIAS**

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
BIASED MOISTURE	0642	DS2502	85/85, 5.5 VOLTS	1000 HRS	80	0	
BIASED MOISTURE	0642	DS2502	85/85, 5.5 VOLTS	1000 HRS	80	0	
<b>Total:</b>						<b>0</b>	